

ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

Material Composition Declaration
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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard http://www.ipc.org/IPC-175x

Form Type\*
Distribute

**Declaration Class\*** Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information			
Company Name *	Company Unique ID	1	Response Date*
Fairchild Semiconductor	00-489-5751	Dun & Bradstreet	Sat, Feb 22, 2014 03:32 AM
Contact Name *	Title - Contact		Email - Contact *
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com
Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Ite	Mfr Item Number Mfr Item Name			Effective Date	Version	N	Manufacturing Site	Weight*	UOM	Unit Type	
LM2904M	LM	2904M	SOIC-8 (AuBW	7)			SUB	CONTRACTOR	0.088017	g	Each	
Manufacturing Process Information												
Terminal Finish	Base Alloy	J-STD-020 MSL Rating			Peak Process Body Temperature		Max Time at Peak Temperature		No Ref	No Reflow cycles		
Matte Tin (Sn)	CU Alloy		1	260		С		30 seconds			3	

<sup>\*</sup> Required Field

## **RoHS Material Composition Declaration**

Declaration Type \* Custom

RoHS Directive 2011/65/EU **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration \*

1 - Item(s) does not contain RoHS restricted substances per the definition above

Supplier Acceptance \* Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

None

**Declaration Signature** 

Supplier Signature

DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

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## **Homogeneous Material Composition Declaration for Electronic Products**

Item/SubItem Name SOIC-8 (AuBW)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	7.100	Supplier		Silicon	7.100	7440-21-3	80667
Die Attach	Other Organic Materials	0.718	Supplier		Acrylic Resin	0.154	54208-63-8	1750
			Supplier		Silver	0.564	7440-22-4	6404
Encapsulation	Thermoplastics	39.400	В	Antimony/Antimony Compounds	Antimony Trioxide	0.788	1309-64-4	8953
			В	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	0.394	6386-73-8	4476
			Supplier		Carbon Black	0.296	1333-86-4	3357
			Supplier		Epoxy Resin	11.426	29690-82-2	129816
			Supplier		Silica, vitreous	26.496	60676-86-0	301040
Lead Frame	Copper & its alloys	38.600	Supplier		Copper	37.531	7440-50-8	426406
			Supplier		Iron	0.926	7439-89-6	10525
			Supplier		Phosphorus	0.015	7723-14-0	175
			Supplier		Silver	0.077	7440-22-4	877
			Supplier		Zinc	0.050	7440-66-6	570
Plating	Other Nonferrous metals & alloys	2.000	Supplier		Tin	2.000	7440-31-5	22723
Wire Bond	Precious metals	0.199	Supplier		Gold	0.199	7440-57-5	2261